

SMT POWER INDUCTORS

Shielded Drum Core - PF0464NL/PF0465NL Series



- Height:** PF0464: 3mm Max - PF0465: 4mm Max
- Footprint:** 7.2mm x 7.2mm Max
- Current Rating:** PF0464: up to 4.5A - PF0465: up to 3.5A
- Inductance Range:** 1.5µH to 100µH

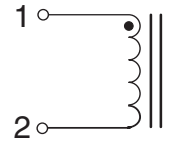
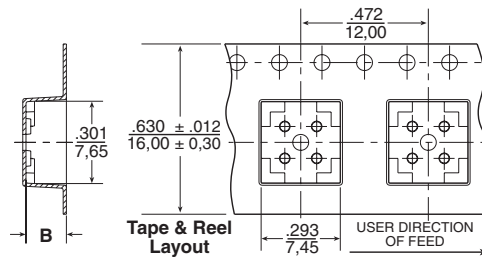
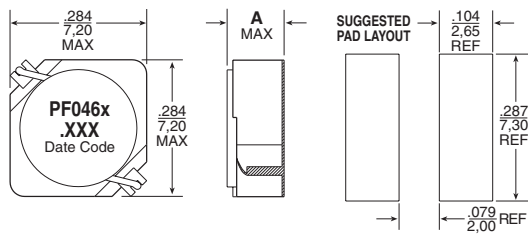
Electrical Specifications @ 25°C — Operating Temperature -40°C to +125°C^{1,6}

Part ^{2,3} Number	Inductance @0A _{dc} (µH ±20%)	Inductance @I _{rated} (µH TYP)	I _{rated} ⁵ (A)	DCR (mΩ)		Saturation ⁶ Current I _{sAT} -20% (A)	Heating ⁷ Current I _{hc} +40°C(A)	Core Loss ⁸ Factor (K2)	SFR (MHz)
				TYP	MAX				
PF0464NL SERIES									
PF0464.152NL	1.5	1.2	4.50	9	12	4.50	5.50	660	>40
PF0464.302NL	3.0	2.4	3.00	17	22	3.00	4.25	850	>40
PF0464.392NL	3.9	3.1	2.60	19	25	2.60	3.80	990	>40
PF0464.502NL	5.0	4.0	2.40	24	30	2.40	3.55	1100	>40
PF0464.602NL	6.0	4.8	2.25	26	33	2.25	3.20	1300	>40
PF0464.732NL	7.3	5.8	2.10	36	45	2.10	3.10	1400	>40
PF0464.862NL	8.6	6.9	1.85	38	48	1.85	2.95	1500	35
PF0464.103NL	10	8.0	1.70	41	52	1.70	2.90	1700	32
PF0464.123NL	12	9.6	1.55	52	66	1.55	2.40	1800	26
PF0464.153NL	15	12.0	1.40	55	75	1.40	2.35	2000	24
PF0464.183NL	18	14.4	1.32	69	90	1.32	2.10	2200	22
PF0464.223NL	22	17.6	1.20	85	113	1.20	1.85	2500	21
PF0464.273NL	27	21.6	1.05	104	132	1.05	1.70	2800	19
PF0464.333NL	33	26.4	0.97	132	165	0.97	1.50	3000	18
PF0464.393NL	39	31.2	0.86	142	180	0.86	1.45	3300	14
PF0464.473NL	47	37.6	0.80	197	238	0.80	1.25	3600	14
PF0464.563NL	56	44.8	0.73	216	270	0.73	1.15	3900	13
PF0464.683NL	68	54.4	0.65	235	300	0.65	1.10	4400	12
PF0464.823NL	82	65.6	0.60	291	370	0.60	1.00	4800	11
PF0464.104NL	100	80.0	0.54	401	505	0.54	0.85	5300	10.5
PF0465NL SERIES									
PF0465.332NL	3.3	2.6	3.50	16	20	3.50	4.65	790	>40
PF0465.502NL	5.0	4.0	2.90	19	24	2.90	4.10	970	>40
PF0465.622NL	6.2	5.0	2.50	21	26	2.50	3.90	1100	>40
PF0465.732NL	7.3	5.8	2.30	25	31	2.30	3.50	1200	>40
PF0465.862NL	8.6	6.9	2.20	27	34	2.20	3.30	1300	35
PF0465.103NL	10	8.0	2.00	29	37	2.00	3.20	1400	32
PF0465.123NL	12	9.6	1.70	39	50	1.70	2.80	1600	26
PF0465.153NL	15	12.0	1.60	44	55	1.60	2.60	1700	24
PF0465.183NL	18	14.4	1.50	62	78	1.50	2.25	1900	22
PF0465.223NL	22	17.6	1.30	68	86	1.30	2.10	2100	21
PF0465.273NL	27	21.6	1.20	75	95	1.20	2.00	2300	19
PF0465.333NL	33	26.4	1.10	94	118	1.10	1.75	2500	18
PF0465.393NL	39	31.2	1.00	101	128	1.00	1.70	2800	17
PF0465.473NL	47	37.6	0.95	112	140	0.95	1.60	3000	14
PF0465.563NL	56	44.8	0.85	154	195	0.85	1.35	3300	13
PF0465.683NL	68	54.4	0.75	188	234	0.75	1.25	3700	12
PF0465.823NL	82	65.6	0.70	261	324	0.70	1.05	4000	11
PF0465.104NL	100	80.0	0.65	286	350	0.65	1.00	4500	10.5

NOTES FROM TABLE: (See page 43)

Mechanical

Schematic



Weight.....0.5 grams0.7 grams
 Tape & Reel1200/reel900/reel
 "A" (height - in./mm)0.118/3,000.158/4,00

"B" height - (in./mm) 0.150/3,80 0.205/5,20

Dimensions: Inches
mm
 Unless otherwise specified,
 all tolerances are ± .004
 0,10

SMT POWER INDUCTORS

Shielded Drum Core Series



Notes from Tables (pages 27 - 42)

1. Unless otherwise specified, all testing is made at 100kHz, 0.1VAC.
2. Optional Tape & Reel packaging can be ordered by adding a "T" suffix to the part number (i.e. P1166.102NL becomes P1166.102NLT). Pulse complies with industry standard Tape and Tape & Reel specification EIA481.
3. The "NL" suffix indicates an RoHS-compliant part number. Non-NL suffixed parts are not necessarily RoHS compliant, but are electrically and mechanically equivalent to NL versions. If a part number does not have the "NL" suffix, but an RoHS compliant version is required, please contact Pulse for availability.
4. Temperature of the component (ambient plus temperature rise) must be within specified operating temperature range.
5. The rated current (I_{rated}) as listed is either the saturation current or the heating current depending on which value is lower.
6. The saturation current, I_{sat}, is the current at which the component inductance drops by the indicated percentage (typical) at an ambient temperature of 25°C. This current is determined by placing the component in the specified ambient environment and applying a short duration pulse current (to eliminate self-heating effects) to the component.
7. The heating current, I_{dc}, is the DC current required to raise the component temperature by the indicated delta (approximately). The heating current is determined by mounting the component on a typical PCB and applying current for 30 minutes. The temperature is measured by placing the thermocouple on top of the unit under test.

8. In high volt*time (Et) or ripple current applications, additional heating in the component can occur due to core losses in the inductor which may necessitate derating the current in order to limit the temperature rise of the component. In order to determine the approximate total loss (or temperature rise) for a given application, both copper losses and core losses should be taken into account.

Estimated Temperature Rise:

$$T_{rise} = [Total\ loss\ (mW) / K0]^{.833}\ (^{\circ}C)$$

$$Total\ loss = Copper\ loss + Core\ loss\ (mW)$$

$$Copper\ loss = I_{RMS}^2 \times DCR\ (Typical)\ (mW)$$

$$I_{rms} = [I_{DC}^2 + \Delta I^2/12]^{1/2}\ (A)$$

$$Core\ loss = K1 \times f\ (kHz)^{1.23} \times B_{ac}(Ga)^{2.38}\ (mW)$$

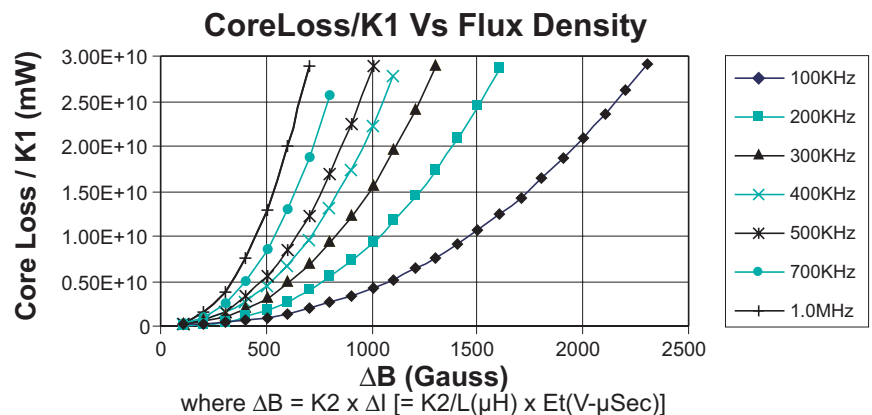
$$B_{ac}\ (peak\ to\ peak\ flux\ density) = K2 \times \Delta I\ (Ga)$$

$$[= K2/L(\mu H) \times Et(V-\mu Sec)\ (Ga)]$$

where f varies between 25kHz and 1MHz, and B_{ac} is less than 2500 Gauss.

K2 is a core size and winding dependant value and is given for each p/n in the proceeding datasheets. K0 & K1 are platform and material dependant constants and are given in the table below for each platform.

Part No.	Trise Factor (K0)	Core Loss Factor (K1)
PG0085/86	2.3	5.29E-10
PG0087	5.8	15.2E-10
PG0040/41	0.8	2.80E-10
P1174	0.8	6.47E-10
PF0601	4.6	14.0E-10
PF0464	3.6	24.7E-10
PF0465	3.6	33.4E-10
P1166	1.9	29.6E-10
P1167	2.1	42.2E-10
PF0560NL	5.5	136E-10
P1168/69	4.8	184E-10
P1170/71	4.3	201E-10
P1172/73	5.6	411E-10
PF0552NL	8.3	201E-10
PF0553NL	7.1	411E-10



Take note that the component's temperature rise varies depending on the system condition. It is suggested that the component be tested at the system level, to verify the temperature rise of the component during system operation.